

X60250

Micro Power Programmable Voltage Reference

FN8146

Rev 1.00

September 14, 2005

FEATURES

- 1.25V 1.0%, 20ppm/°C Tempco Reference
- Adjustable to $\pm 0.25\%$ Over the 0 to 1.25V Range
- 8 bit, 100k Ω XDCP on-chip
- Programmable Resolution of 4.9mV (255 steps)
- Extra Matched 100k Ω Resistor Available for Increased Resolution Over a Smaller Range
- 2.7V to 5.5V Supply Range
- 2-Wire Interface for Programming Reference Setting
- Low Supply Current: 12 μ A in Normal Mode
- 8-pin TSSOP Package
- Programmable Reference
- NV Memory
- Pb-Free Plus Anneal Available (RoHS Compliant)

PROGRAMMABLE VOLTAGE REFERENCE APPLICATIONS

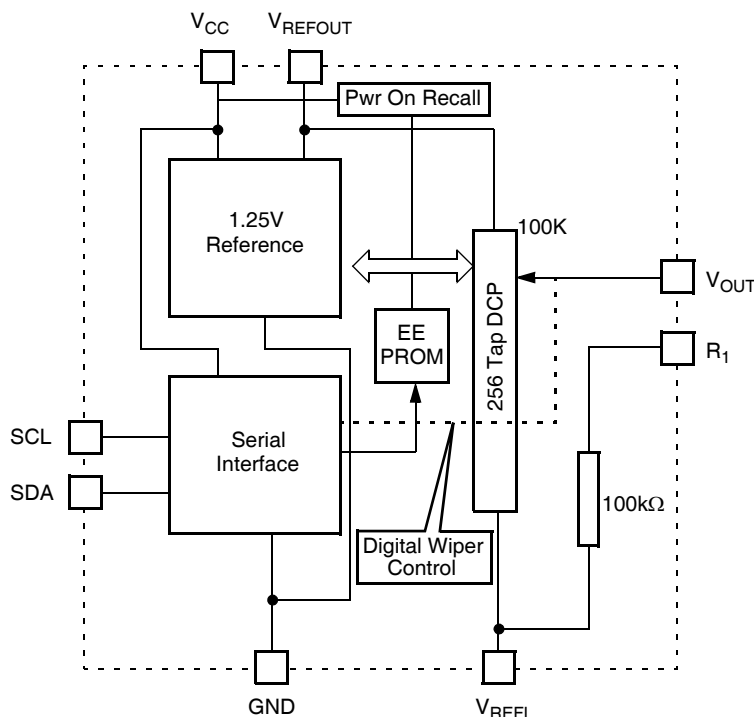
- Sensor Bias
- Variable DAC reference
- Linear Voltage Regulators
- DC/DC converters
- Voltage comparators
- Motor controllers
- Amplifier biasing

DESCRIPTION

The Intersil X60250 combines a temperature compensated voltage reference with a Intersil Digitally Controlled Potentiometer (XDCP) to provide a precision adjustable reference with a range of 0.0V to 1.25V. The device includes a serial bus interface to enable in-circuit programming of the reference voltage.

The XDCP contains a resistor chain with 255 taps to provide 8 bits of digital adjustment to the reference voltage. Non-volatile storage retains the digital wiper setting, for permanent reference programming. An additional matched 100k Ω resistor is available to increase resolution of the output voltage while retaining accuracy.

IC BLOCK DIAGRAM

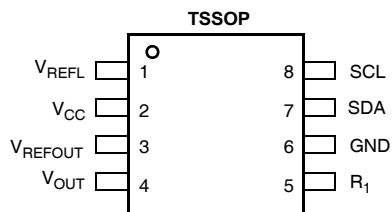


Ordering Information

PART NUMBER	PART MARKING	OUTPUT VOLTAGE (V)	RESOLUTION	TEMP RANGE (°C)	PACKAGE
X60250V8I	60250 I	1.250	8 bits	-40 to 85	8 Ld TSSOP
X60250V8IZ (Note)	60250I Z	1.250	8 bits	-40 to 85	8 Ld TSSOP (Pb-free)

NOTE: Intersil Pb-free plus anneal products employ special Pb-free material sets; molding compounds/die attach materials and 100% matte tin plate termination finish, which are RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.

PIN CONFIGURATION



PIN ASSIGNMENTS

TSSOP	Symbol	Description
1	V_{REFL}	DCP and auxiliary resistor reference input
2	V_{CC}	Positive Power Supply
3	V_{REFOUT}	Bandgap Reference Output
4	V_{OUT}	DCP Wiper Output
5	R_1	Auxiliary resistor input
6	GND	Ground
7	SDA	Serial Data Input/Output
8	SCL	Serial Clock Input

ABSOLUTE MAXIMUM RATINGS

Supply Voltage Range.....-1V to 7V
 Bias Temperature Range -40°C to +85°C
 Storage Temperature Range..... -65°C to +150°C
 Voltage on V_{REF(Low)} pin0V to V_{CC}
 Voltage on all other pins-0.3V to V_{CC}+0.3V
 Lead temperature (soldering, 10 seconds)..... 300°C

RECOMMENDED OPERATING CONDITIONS

	Min	Max
Temperature	-40°C	+85°C
Supply Voltage	2.7V	5.5V

COMMENTS

Absolute Maximum Ratings indicate limits beyond which permanent damage to the device and impaired reliability may occur. These are stress ratings provided for information only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification are not implied.

For guaranteed specifications and test conditions, see Electrical Characteristics.

The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.

ELECTRICAL CHARACTERISTICS

(Over operating conditions unless otherwise specified. I_{OUT} = 12.5 μA, R₁ = N/C (Floating).)

ANALOG PARAMETERS

Symbol	Parameter	Limits				Test Conditions
		Min.	Typ. (1)	Max.	Unit	
Power Supply						
V _{CC}	Supply Voltage Range	2.7	3.0	5.5	V	
I _Q	Supply Current V _{CC} = 2.7V V _{CC} = 3V V _{CC} = 5.5V Write		15	20 60	μA	R _L =0, V _{REFL} , V _{OUT} , R _{AUX} = floating
I _{Q(NV)}	Non-Volatile Supply Current V _{CC} = 2.7V V _{CC} = 3V V _{CC} = 5.5V		600	1100 1300	μA	R _L =0, V _{REFL} , V _{OUT} , R _{AUX} = floating
Reference Output Voltage						
DC Parameters						
V _{REFOUT}	Output Voltage	1.237	1.250	1.263	V	T _A = 25°C
V _{REFL}	DCP and auxiliary resistor reference input	GND		V _{REFOUT}	V	
TC _{oref}	Temperature coefficient of V _{REF} output voltage		20	70	ppm/°C	(2, 5)
PSRR	Power Supply Rejection	55	66		dB	(6)
I _{OUT}	Output Current Sourcing Sinking		1	400	μA	(2)
R _{OUT}	Output Impedance		1	2.5	Ω	Given by R _{OUT} = (ΔV _{REF} /ΔI _{OUT}) (2)
I _{SC}	Short Circuit Current Sourcing Sinking		5 0		mA	At 5.5V
C _L	Load Capacitance		0.001	0.003	μF	Reference output stable for all CL up to specifications (2)

ANALOG PARAMETERS (CONTINUED)

Symbol	Parameter	Limits				Test Conditions
		Min.	Typ. (1)	Max.	Unit	
AC Parameters						
V _N	Output Voltage Noise		100 200		μVP-P μVRMS	0.1Hz to 10Hz (2) 10Hz to 10kHz (2)
	Power-on Response		250		μs	1% Settling (2)
	Line Ripple Rejection		60		dB	V _{DD} = 3V ±100mV, f = 120 Hz (2)
Reference DCP						
	Resolution			8	bits	
R _{TOT}	End to end resistance	85	100	115	kΩ	
R _W	Wiper Resistance V _{CC} = 2.7V V _{CC} = 3V		600	5000 1200	Ω	(2)
	Absolute Linearity (INL)		±0.2		LSB	
	Relative Linearity (DNL)		±0.1		LSB	
	R _{TOT} Temperature Coeff.		±300		ppm/°C	
	Ratiometric Temp. Coeff.		±20		ppm/°C	
R_{AUX} (Auxiliary Resistor)						
R _{TOT}	End to end resistance	85	100	115	kΩ	
	R _{TOT} Temperature Coeff.		±300		ppm/°C	R _L =0, V _{REFL} , V _{OUT} , R _{AUX} = floating
	DCP Matching Tolerance		0.1		%	
	DCP Matching Temp. Coeff.		±20		ppm/°C	

DIGITAL PARAMETERS

Symbol	Parameter	Limits				Test Conditions
		Min.	Typ. (1)	Max.	Unit	
I _{LI}	Input Leakage Current			2	μA	V _{IN} = GND to V _{CC}
I _{LO}	Output Leakage Current			2	μA	V _{OUT} = GND to V _{CC}
V _{IL}	Input Low Voltage	0		V _{CC} × 0.2	V	
V _{IH}	Input High Voltage	V _{CC} × 0.7		V _{CC}	V	
C _{IN}	Input Capacitance		5		pF	
V _{OL}	Output Low Voltage	0		10	%V _{DD}	I _{OL} = 100 μA (2)
V _{OH}	Output High Voltage	90		100	%V _{DD}	I _{OH} = 100 μA (2)
C _L	Output Load			100	pF	(2)

EEPROM PARAMETERS (Erase at V_{CC} = 5.0 V min, T = 25°C)

Parameter	Min.	Units
Write Cycle Endurance	100,000	Cycles per bit

CAPACITANCE

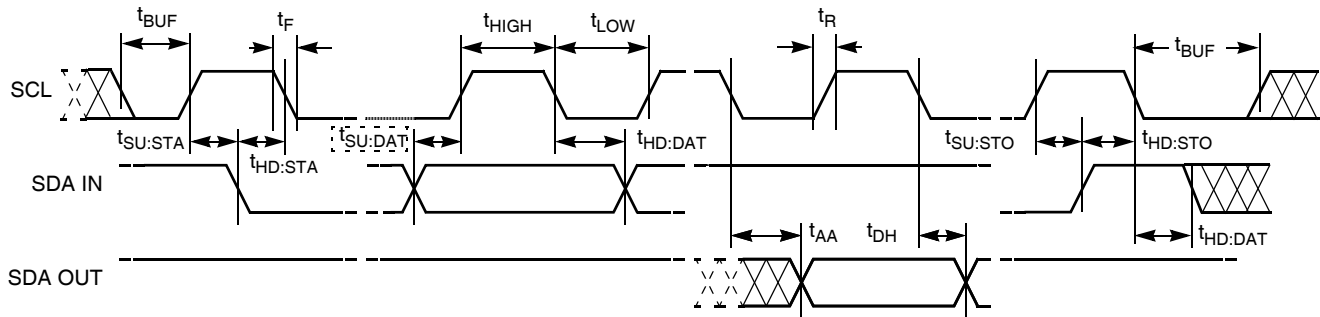
Symbol	Test	Max.	Units	Test Conditions
C _{IN/OUT}	Input/Output capacitance (SDA)	8	pF	V _{OUT} = 0V (2)
C _{IN}	Input capacitance (SCL)	6	pF	V _{IN} = 0V (2)

A.C. TEST CONDITIONS

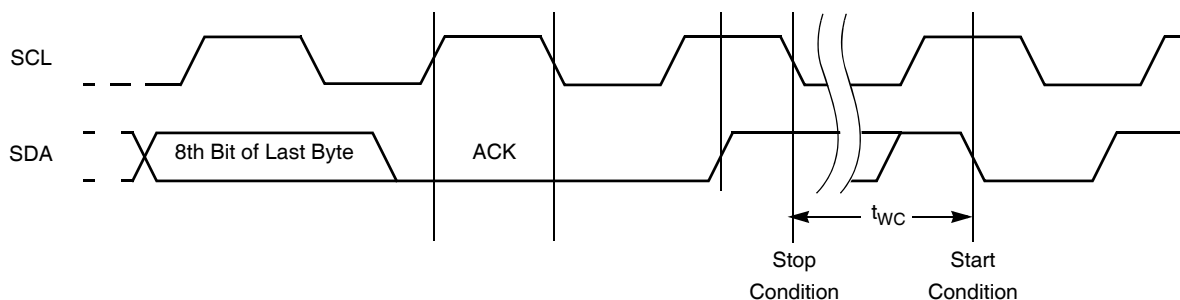
Input Pulse Levels	$V_{CC} \times 0.1$ to $V_{CC} \times 0.9$
Input rise and fall times	10ns
Input and output timing threshold level	$V_{CC} \times 0.5$
External load at pin SDA	$2.3k\Omega$ to V_{CC} and 100 pF to V_{SS}

AC SPECIFICATIONS

Symbol	Parameter	Min.	Max.	Unit
f_{SCL}	SCL Clock Frequency	0	400	kHz
t_{IN}	Pulse width Suppression Time at inputs ⁽²⁾	50		ns
t_{AA}	SCL LOW to SDA Data Out Valid ⁽²⁾	0.1	0.9	μ s
t_{BUF}	Time the bus must be free before a new transmission can start ⁽²⁾	1.3		μ s
t_{LOW}	Clock LOW Time	1.3		μ s
t_{HIGH}	Clock HIGH Time	0.6		μ s
$t_{SU:STA}$	Start Condition Setup Time	0.6		μ s
$t_{HD:STA}$	Start Condition Hold Time	0.6		μ s
$t_{SU:DAT}$	Data In Setup Time	100		ns
$t_{HD:DAT}$	Data In Hold Time	0		μ s
$t_{SU:STO}$	Stop Condition Setup Time ⁽²⁾	0.6		μ s
t_{DH}	Data Output Hold Time ⁽²⁾	50		ns
t_R	SDA and SCL Rise Time ^(2, 3)	$20 + .1Cb$	300	ns
t_F	SDA and SCL Fall Time ^(2, 3)	$20 + .1Cb$	300	ns
C_b	Capacitive load for each bus line ^(2, 3)		400	pF

TIMING DIAGRAMS**Bus Timing**

WRITE CYCLE TIMING



POWER-UP TIMING

Symbol	Parameter	Min.	Max.	Unit
$\Delta V_{CC}/\Delta t$	V_{CC} Power-up rate (2)	0.2	50	V/ms
t_{PUR}	Time from Power-up to Read (2)		1	ms
t_{PUW}	Time from Power-up to Write (2)		5	ms

NONVOLATILE WRITE CYCLE TIMING

Symbol	Parameter	Min.	Typ.	Max.	Unit
t_{WC}	Write Cycle Time (4)		5	10	ms

- Notes: (1) Typical values are for $T_A = 25^\circ\text{C}$ and $V_{CC} = 3.0\text{V}$
 (2) This parameter is guaranteed by characterization.
 (3) C_b = total capacitance of one bus line in pF.
 (4) t_{WC} is the time from a valid stop condition at the end of a write sequence to the end of the self-timed internal nonvolatile write cycle. It is the minimum cycle time to be allowed for any nonvolatile write by the user, unless Acknowledge Polling is used.
 (5) Over the specified temperature range. Temperature coefficient is measured by the box method whereby the change in V_{OUT} is divided by the temperature range; in this case, -40°C to $+85^\circ\text{C} = 125^\circ\text{C}$. $TC_{Oref} = [\text{Max } V(V_{REF}) - \text{Min } V(V_{REF})] \times 10^6 / (1.25\text{V} \times 125^\circ\text{C})$

FUNCTIONAL DESCRIPTION

The X60250 combines a micropower precision reference with an 8-bit, 256 tap digitally controlled 100k Ω potentiometer (DCP) which allows nonvolatile setting of an output reference voltage. When normally configured with the V_{REFL} pin tied to ground, the device provides an output range of 0V to 1.25V with 4.90mV resolution.

The device can also be configured with an optional 100k Ω series resistor to ground, which effectively halves the output voltage range while doubling the resolution. Grounding the R_1 pin while floating the V_{REFL} pin places the device in this mode. Output voltage setting accuracy can be as high as 0.10% while permitting adjustment from 0.625V to 1.25V (2.45mV resolution).

Reference Section

The reference is designed to provide an accurate, low tempco voltage source while requiring less than 12 μ A (typical) of supply current. This supply current is for the reference section only. Keep in mind that the DCP will increase supply current draw by V_{REF}/R_{TOTAL} (typically 1.25/100k or 12.5 μ A). The total current drawn by the adjustable reference circuit will be less than 25 μ A (typically).

The reference output has a typical impedance of 1 Ω and can provide up to 400 μ A of load current. It is intended to drive the resistive load of the DCP, which is a minimum of 85k Ω , but can also be used to drive off chip circuitry provided the loading does not exceed the 400 μ A maximum. Also, highly capacitive loads can make the reference oscillate, so no more than 2000pF should be placed directly on the output of the V_{REFOUT} pin.

The reference output produces about 200 μ V RMS of noise (10kHz bandwidth) due to its micropower design. This is easily reduced in normal applications, as shown in the applications section for optimizing circuits for reducing output noise levels.

DCP Section

The 256 tap DCP has an 8-bit nonvolatile wiper control register which controls which tap is selected. The register is changed by performing a serial data write to its address (0h, see Serial Interface section). The resulting wiper position will produce an output voltage at V_{OUT} , depending on whether the DCP V_{REFL} is grounded or the R_1 pin is grounded. The wiper consists of CMOS transistors and has a finite resistance, typically 600 Ω at $V_{CC} = 5V$ (this parameter increases with decreasing V_{CC}). The wiper resistance will produce errors in reference circuits due to I-R drops if current flows through the wiper. However, typically these circuits will have the wiper connected to a high impedance comparator or amplifier input which results in very small wiper currents and thus only a small output

voltage error. If the X60250 is used with the wiper connected to V_{REFL} to produce a current source, care must be taken to avoid exceeding the maximum output current of the reference (typically 400 μ A).

Power-Up considerations

The X60250 contains EEPROM nonvolatile storage cells which are recalled during power-up. This recall process works best with power supply (V_{CC}) ramping that is monotonic and free of excessive glitches (<100mV disturbances give best results). The ramp rate spec should be adhered to, although the most sensitive part of recall is between $V_{CC} = 1.0V$ and 2.5V. Effort should be made to make sure the device receives a power-up ramp between those voltage levels that meet the ramp rate spec and have no glitches.

Recall of the stored wiper position happens in < 1ms from V_{CC} reaching 2.5V. Note that any excursions of V_{CC} below 2.5V, although temporary, can cause the wiper to be loaded with the midpoint value (80h) until V_{CC} recovers to its normal voltage.

Register Organization

There are 2 nonvolatile registers and 1 volatile register available for storage and recall via the serial bus. They contain the current wiper position, a general purpose data register and a status register.

The wiper register is nonvolatile and is at address 0h and contains 8 bits, with the 00h setting corresponding to the tap position nearest V_{REFL} , and the FFh setting nearest to V_{REFOUT} .

The general purpose register is nonvolatile and is at address 1h, and contains 8 bits for use as scratchpad memory or serial number information.

The Status register is volatile and is at address 7h. It has one active bit, D3, which is the WEL bit. This bit must be set to 1 before any nonvolatile writes are performed to the other registers. See the register information on the next page.

X60250 REGISTER BIT MAP

Addr	D7	D6	D5	D4	D3	D2	D1	D0
0	D7 (MSB)	D6	D5	D4	D3	D2	D1	D0 (LSB)
1	D7 (MSB)	D6	D5	D4	D3	D2	D1	D0 (LSB)
7	0	0	0	0	WEL	0	0	0

REGISTER DESCRIPTIONS

Reg	Nonvolatile	Description
0	Y	V _{OUT} wiper setting
1	Y	General Purpose data storage register
7	N	Status register

REGISTER 0 (NONVOLATILE)

This register is used to hold the DCP wiper position, which is given by:

$$V_{OUT} = V_{REF} \times \frac{\text{Code}}{255} \quad (\text{with } V_{REFL} = \text{GND})$$

REGISTER 1 (NONVOLATILE)

This 8 bit register is used for general storage such as date code, temp setting, etc.

STATUS REGISTER

Bit	Value	Description
D - D4	0	Must remain 0
D3	0 - 1	WEL bit Must be programmed to "1" for Reg 0 or 1 EEPROM write. When accessing, only WEL bit may be changed
D2 - D0	0	Must remain 0

X60250 BUS INTERFACE INFORMATION

Figure 1. Slave Address, Word Address, and Data Bytes - Write Mode

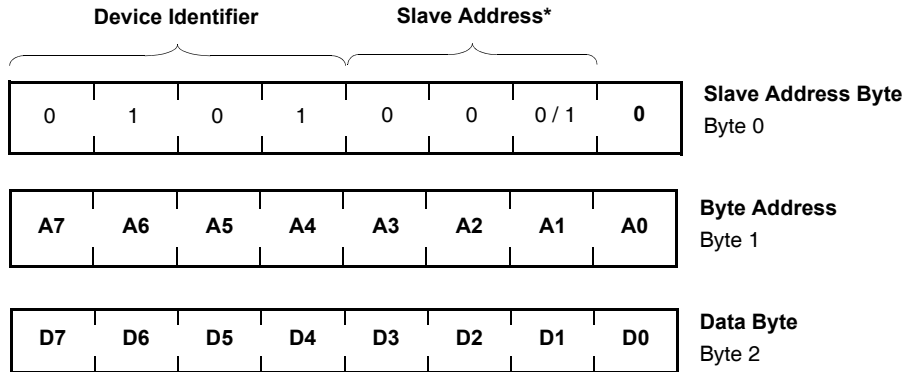
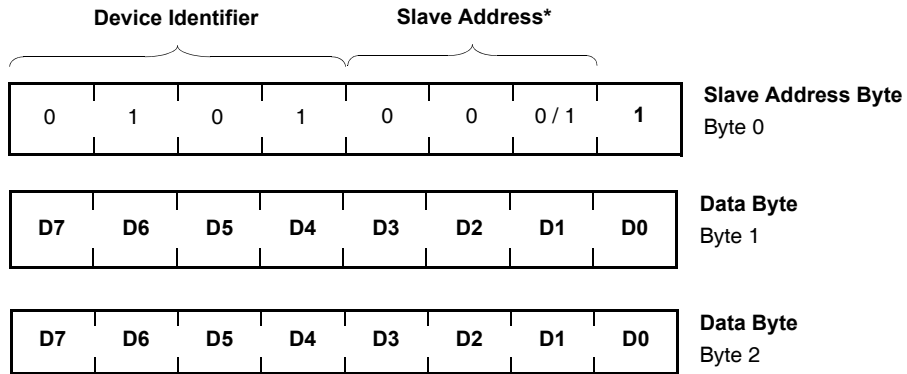


Figure 2. Slave Address, Word Address, and Data Bytes - Read Mode



X60250 BUS INTERFACE INFORMATION

Slave Address, Address Byte, and Data Byte

The byte communication format for the serial bus is shown in Figure 1 on the previous page. The first byte, BYTE 0, defines the device identifier, 0101 in the upper half; and the device slave address in the low half of the byte. The slave address is set to 0. The next byte, BYTE 1, is the Address Byte. The Address Byte identifies a unique address for the Status or Control Registers as shown in the Register Descriptions table. The following byte, Byte 2, is the byte used for READ and WRITE operations.

Start Condition

All commands are preceded by the start condition, which is a HIGH to LOW transition of SDA when SCL is HIGH. The device continuously monitors the SDA and SCL lines for the start condition and will not respond to any command until this condition has been met. On power-up, the SCL pin must be brought LOW prior to the START condition. See Figure 3.

Stop Condition

All communications must be terminated by a stop condition, which is a LOW to HIGH transition of SDA when SCL is HIGH followed by a HIGH to LOW transition on SCL. After going LOW, SCL can stay LOW or return to HIGH. See Figure 3.

Acknowledge

Acknowledge is a software convention used to indicate successful data transfer. The transmitting device, either master or slave, will release the bus after transmitting eight bits. During the ninth clock cycle, the receiver will pull the SDA line LOW to acknowledge that it received the eight bits of data. Refer to Figure 4. The device will respond with an acknowledge after recognition of a start condition and if the correct Device Identifier and Select bits are contained in the Slave Address Byte. If a write operation is selected, the device will respond with an acknowledge after the receipt of each subsequent eight bit word. The device will acknowledge all incoming data and address bytes, except for:

- The Slave Address Byte when the Device Identifier and/or Select bits are incorrect
- The 2nd Data Byte of a Status Register Write Operation (only 1 data byte is allowed)

Pin Descriptions

V_{REFOUT}

Reference voltage output. The 1.25V bandgap reference output (V_{REF}) is available at this pin for application to other circuits. Maximum output current is 400μA. The V_{REFOUT} pin also connects to the Rh terminal of the 256-tap DCP.

V_{OUT}

DCP Wiper Output. This pin functions as the wiper of the DCP, and can be used as a variable voltage source for voltages between GND and V_{REF}. Since it is connected to the DCP resistor, any loads on this pin must be high impedance for best performance.

R₁

Auxiliary Resistor Input. The R₁ pin is connected to one end of a 100kΩ resistor (R₁) which closely matches the DCP resistance. The other end of R₁ is tied to the R_{REFL} terminal of the DCP. When R₁ is grounded and V_{REFL} is left open, the output voltage range of V_{OUT} will be from V_{REF}/2 to V_{REF}, and the effective resolution (mV/step) of the Reference control is doubled. R₁ should be left open if not used.

GND

This pin is common for the V_{REF} output and for control signal inputs.

SDA

Serial Data Input/Output. Bidirectional pin used for serial data transfer. As an output, it is open drain and may be wire-ored with any number of open drain or open collector outputs. A pullup resistor is required and the value is dependent on the speed of the serial data bus and the number of outputs tied together.

SCL

Serial Clock Input. Accepts a clock signal for clocking serial data into and out of the device.

V_{REFL}

DCP and Auxiliary Resistor Input. This pin is connected to one end of the 256-tap DCP, and also to one end of the 100kΩ auxiliary resistor. When connected to ground, V_{OUT} range will be from 0V to V_{REF}. When left open and R₁ is connected to ground, the voltage at this pin will be from V_{REF}/2 to V_{REF}.

V_{CC}

Positive Power Supply. Connect to a voltage supply in the range of $2.7V < V_{CC} < 5.5V$, with minimum noise and ripple. For best performance, bypass with a $0.1\mu F$ capacitor to ground.

Figure 3. Valid Start and Stop Conditions

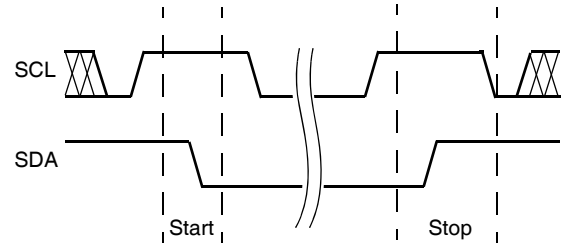


Figure 4. Acknowledge Response From Receiver

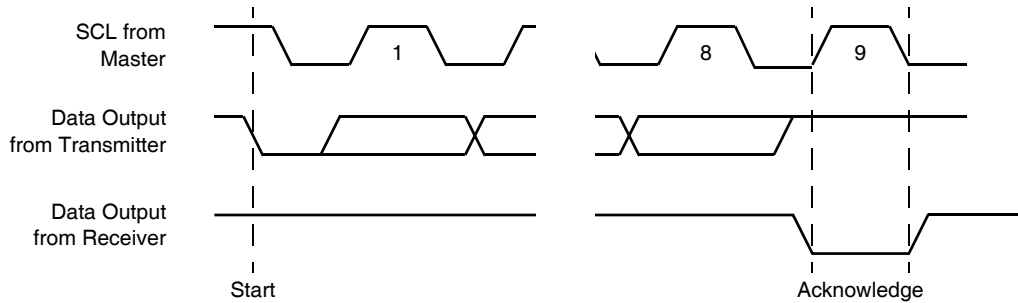


Figure 5. Valid Data Changes on the SDA Bus

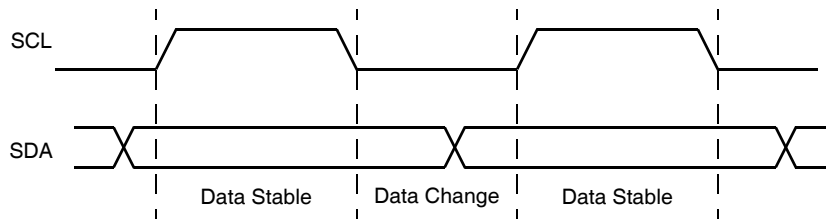
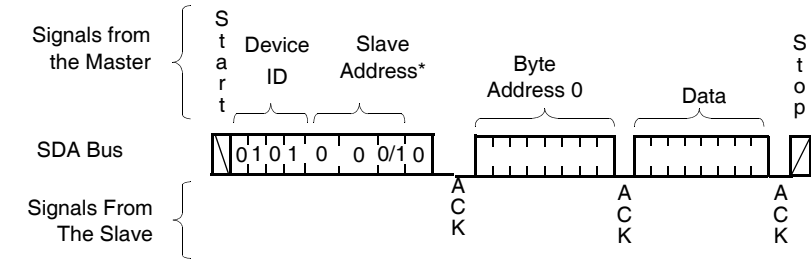


Figure 6. Byte Write Sequence



*Note: The X60250 will respond to either 000 or 001 slave addresses.

Byte Write

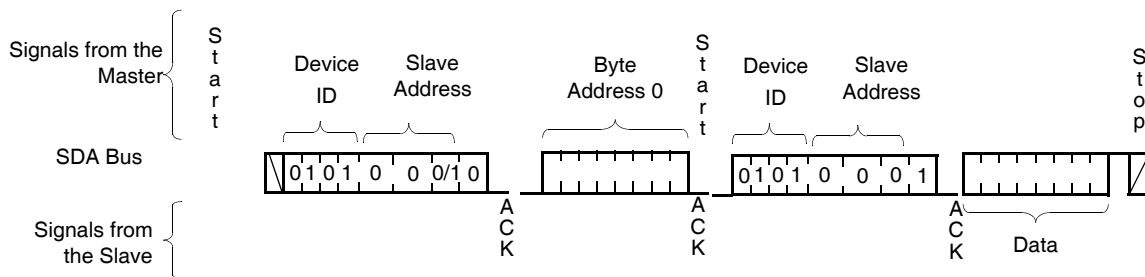
For a write operation, the device requires the Slave Address Byte and the Word Address Bytes. This gives the master access to any one of the words in the array. Upon receipt of each address byte, the X60250 responds with an acknowledge. After receiving the address bytes the X60250 awaits the eight bits of data. After receiving the 8 data bits, the X60250 again responds with an acknowledge. The master then terminates the transfer by generating a stop condition. The X60250 then begins an internal write cycle of the data to the nonvolatile memory. During the internal write cycle, the device inputs are disabled, so the device will not respond to any requests from the master. The SDA output is at high impedance. See Figure 6.

A write to a protected block of memory is ignored, but will still receive an acknowledge. At the end of the write command, the X60250 will not initiate an internal write cycle, and will continue to okay commands.

Stops and Write Modes

Stop conditions that terminate write operations must be sent by the master after sending at least 1 full data byte and its associated ACK signal. If a stop is issued in the middle of a data byte, or before 1 full data byte + ACK is sent, then the X60250 resets itself without performing the write. The contents of the array are not affected.

Figure 7. Random Address Read Sequence



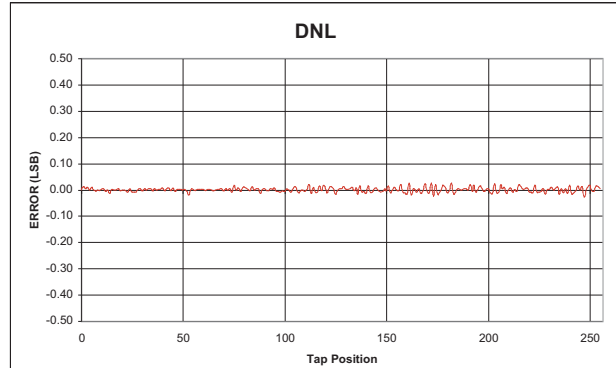
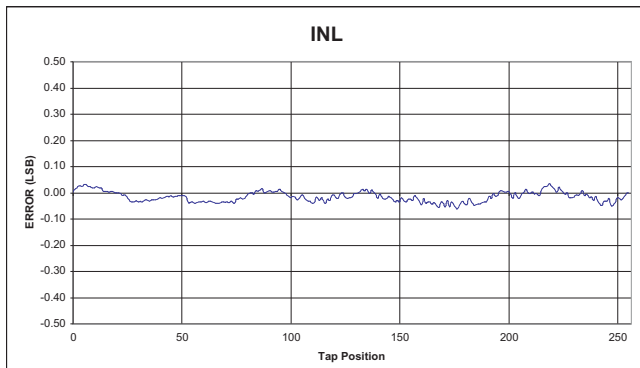
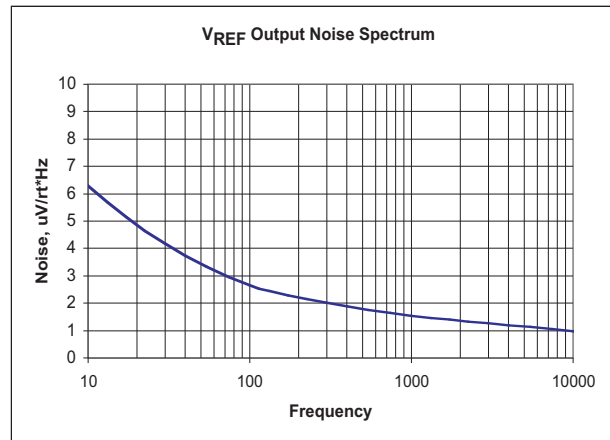
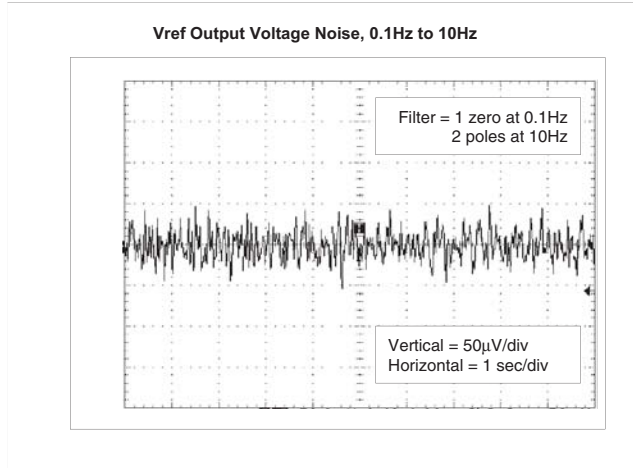
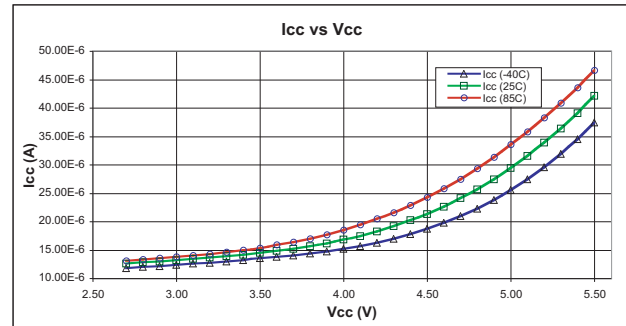
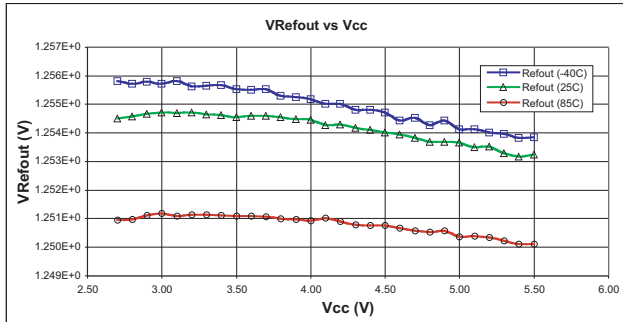
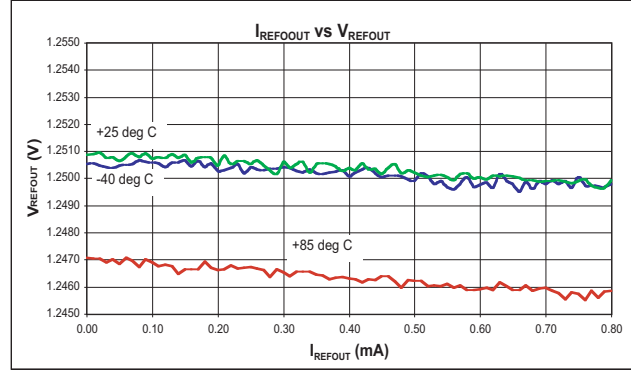
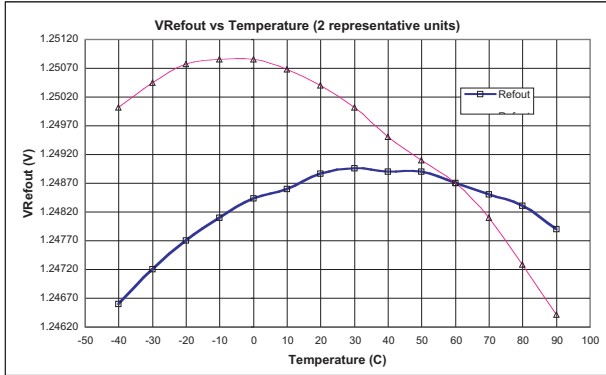
Random Address Read

Random read operation allows the master to access any location in the X60250. Prior to issuing the Slave Address Byte, the master must first perform a “dummy” write operation.

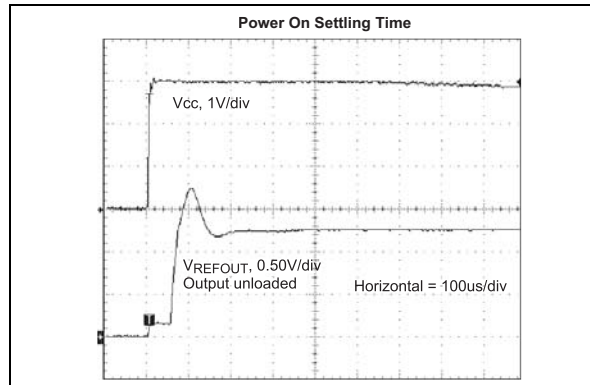
In a similar operation called “Set Current Address,” the device sets the address if a stop is issued instead of the second start shown in Figure 7. The X60250 then goes into standby mode after the stop and all bus activity will be ignored until a start is detected. This operation loads the new address into the address counter. The next Current Address Read operation will read from the newly loaded address. This operation could be useful if the master knows the next address it needs to read, but is not ready for the data.

The master issues the start condition and the slave address byte, receives an acknowledge, then issues the word address bytes. After acknowledging receipt of each word address byte, the master immediately issues another start condition and the slave address byte. This is followed by an acknowledge from the device and then by the eight bit data word. The master terminates the read operation by not responding with an acknowledge and then issuing a stop condition. Refer to Figure 7 for the address, acknowledge, and data transfer sequence.

TYPICAL PERFORMANCE CHARACTERISTIC CURVES



TYPICAL PERFORMANCE CHARACTERISTIC CURVES (Continued)



APPLICATIONS INFORMATION

Standard Reference configurations

Figure 8 shows the device connections to produce a 0 to 1.250V adjustable reference with 8 bits of resolution. V_{REFL} will be grounded in this case. Figure 9 has device connections to produce a 0.625V to 1.250V reference with 8 bits of resolution, with R_1 grounded. This configuration effectively doubles the output voltage control resolution, increasing the accuracy of the desired reference output voltage. Since the auxiliary resistor is matched to the DCP resistor, temperature drift is minimized.

Figure 8. Standard Configuration

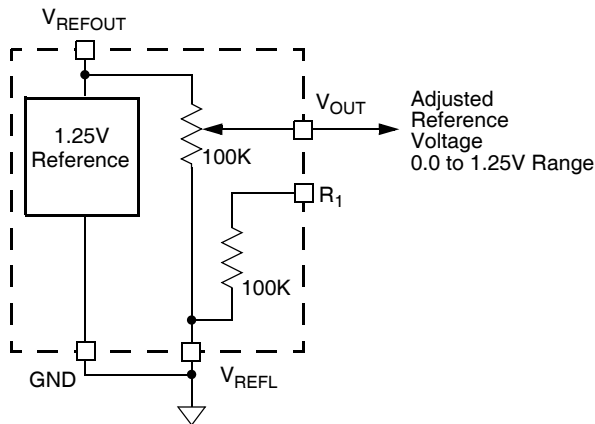
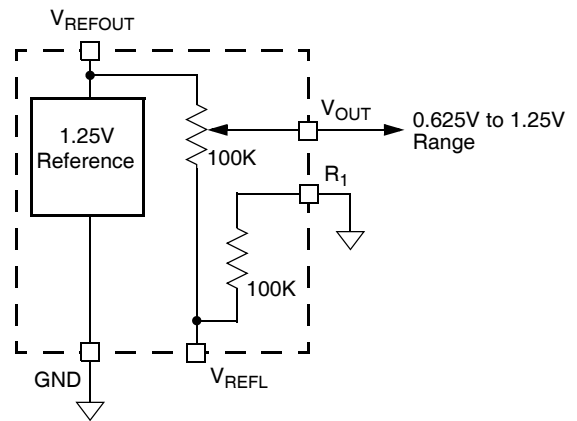


Figure 9. Using Auxilliary Resistor



Reducing Output Noise

The output noise voltage of the reference is typically 200 μ V rms in the 10kHz bandwidth. An advantage of the adjustable reference configuration is the ease in filtering this noise. Simply adding a capacitor to the V_{OUT} pin will produce a single pole filter with a corner frequency of:

$$F_{CORNER} = \frac{1}{2} \times \pi \times R_{DCP} \times C_{FILTER}$$

R_{DCP} will vary with tap position and wiper resistance. If the approximate tap position of the DCP is known, it can be used to calculate this resistance as follows:

$$R_{DCP} = \frac{255 - tap\#}{255} \times \left[R_{TOTAL} \parallel \left(\frac{tap\#}{255} \times R_{TOTAL} \right) \right] + R_{WIPER}$$

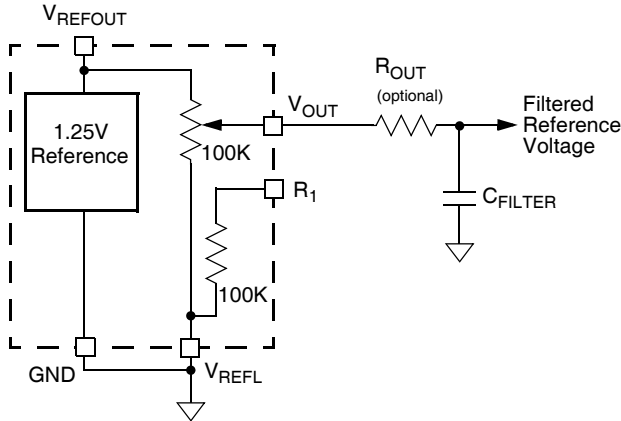
For example, with $V_{CC} = 5V$, tap # = 127 (corresponding to $V_{OUT} = 0.623V$), $C_{FILTER} = 0.1\mu F$, using typical values:

$$R_{DCP} = 25K + 0.6K = 25.6k\Omega$$

$$F_{CORNER} = 62Hz$$

Since this is a single pole rolloff, the actual noise bandwidth is 1.57 times this, or 97Hz. This should reduce typical output noise to about 45 μ V rms. Note that if the wiper is set to the highest tap position (tap# = 255) to give a V_{OUT} of 1.25V, the resulting $R_{DCP} = R_{WIPER}$ or 600 Ω , and the filter bandwidth will now be 2.6kHz, increasing noise significantly. If tap positions near V_{REFOUT} will be used, then a series resistor R_{OUT} should be added to better control noise bandwidth.

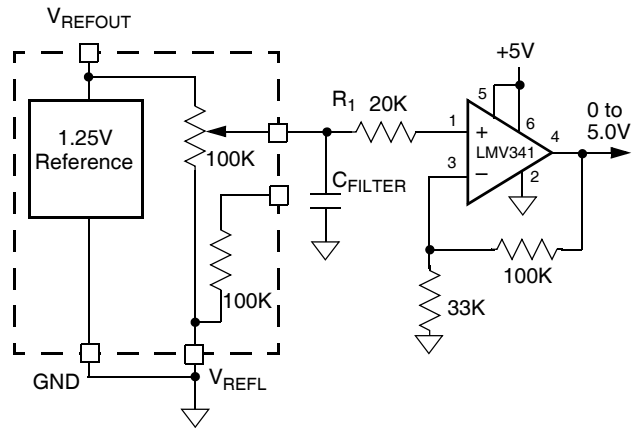
Figure 10. Reducing Output Noise



Higher Reference Voltages

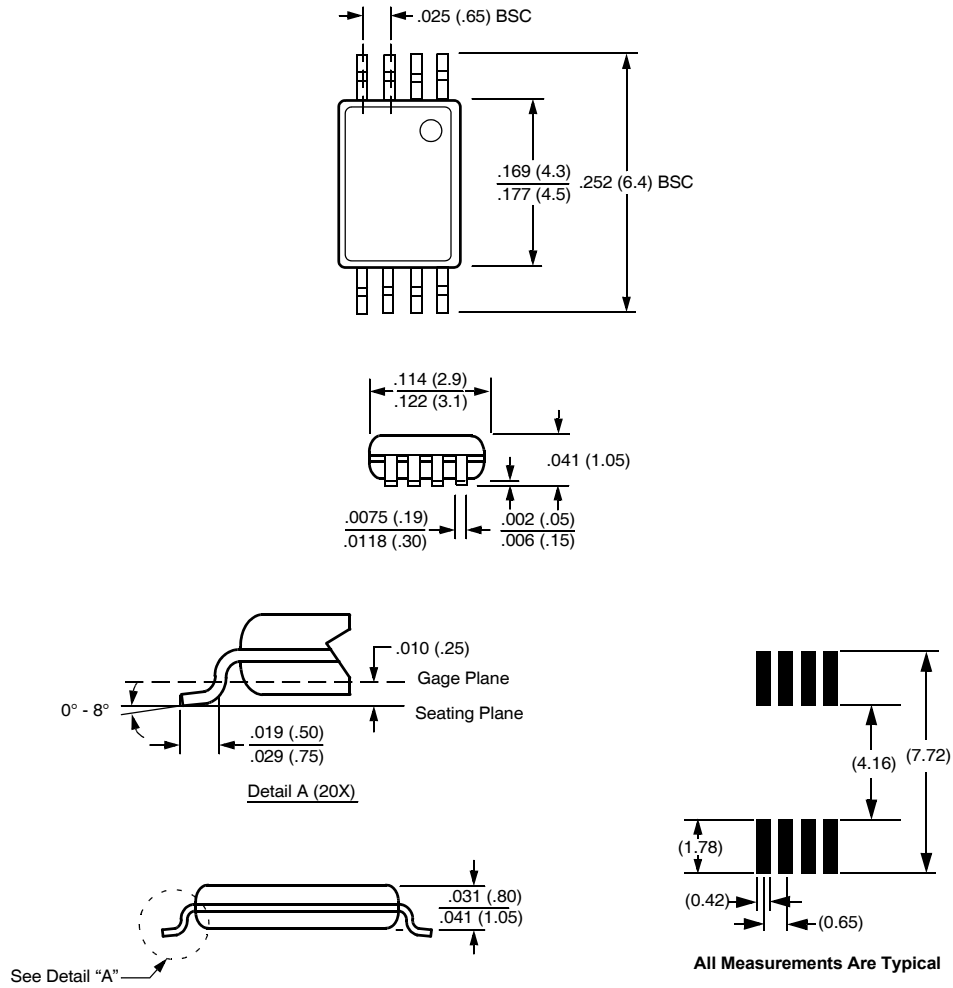
If a reference voltage higher than 1.25V is required, then an opamp can be added to amplify the V_{OUT} voltage. There are many micropower opamps available, such as the LMV341, which can produce an output at very close to either supply rail. Figure 11 shows a circuit for a 0V to 5.0V adjustable reference, which has 8 bits of control. Note that if the auxiliary resistor is connected to ground instead of V_{REFL} , then the output voltage range will be 2.5V to 5.0V, but resolution will double. Total current draw from that circuit will be 156 μ A (typically, with $V_{OUT} = 5V$) including reference and opamp circuitry. Note that due to V_{CC} supply variations, the output may not span up to 5.00V which would result in missing codes at the top end of the DCP range.

Figure 11. Increasing Reference Output Voltage



PACKAGING INFORMATION

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